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Field device tool (FDT) interface specification - Part 51-31: Communication implementation for common object model - IEC 61784 CP 3/1 and CP 3/2 (IEC/TR 62453-51-31:2017)

Spécification des interfaces des outils des dispositifs de terrain (FDT) - Partie 51-31: Mise en œuvre d'un profil de communication pour le modèle d'objet commun - CP 3/1 et CP 3/2 de l'IEC 61784 (IEC/TR 62453-51-31:2017) Field Device Tool (FDT)-Schnittstellenspezifikation - Teil 51-31: Kommunikationsimplementierung mit dem allgemeinen Objektmodell (COM) -Kommunikationsprofilfamilie (CPF) 3/1 und 3/2 nach IEC 61784 (IEC/TR 62453-51-31:2017)

This Technical Report was approved by CENELEC on 2019-01-07.

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European Committee for Electrotechnical Standardization Comité Européen de Normalisation Electrotechnique Europäisches Komitee für Elektrotechnische Normung

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European foreword

This document (CLC/TR 62453-51-31:2019) consists of the text of the IEC/TR 62453-51-31:2017 prepared by IEC/TC 65 "Industrial-process measurement, control and automation".

Endorsement notice

The text of the International Standard IEC/TR 62453-51-31:2017 was approved by CENELEC as a European Standard without any modification.

<text>

Annex ZA

(normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

Publication	Year	<u>Title</u> <u>EN/HD</u>	Year
IEC 61158	Series	Industrial communication networks - Fieldbus EN 61158 specifications	Series
IEC 61784-1	2014	Industrial communication networks - Profiles - EN 61784-1 Part 1: Fieldbus profiles	2014
IEC 62453-1	2016	Field device tool (FDT) interface specification EN 62453-1 - Part 1: Overview and guidance	2017
IEC 62453-2	2016	Field device tool (FDT) interface specification EN 62453-2 - Part 2: Concepts and detailed description	2017
IEC/TR 62453-41	2016	Field device tool (FDT) interface specification - - Part 41: Object model integration profile - Common object model	-
IEC 62453-303-1	2009	Field device tool (FDT) interface specification EN 62453-303-	1 2009
+ A1	2016	- Part 303-1: Communication profile + A1 integration - IEC 61784 CP 3/1 and CP 3/2	2018

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

FIELD DEVICE TOOL (FDT) INTERFACE SPECIFICATION -

Part 51-31: Communication implementation for common object model – IEC 61784 CP 3/1 and CP 3/2

FOREWORD

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IEC TR 62453-51-31, which is a echnical report, has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process management, control and automation.

This document cancels and replaces IEC TR 62453-503-1 published in 2009. This edition constitutes a technical revision. The main changes consist of updates in accordance with IEC 62453-2 in regard to the description of "Composite Device DTM".

IEC TR 62453-51-31:2017 © IEC 2017 - 5 -

Each part of the IEC 62453-51-xy series is intended to be read in conjunction with its corresponding part in the IEC 62453-3xy series. This document corresponds to IEC 62453-303-1.

The text of this technical report is based on the following documents:

Enquiry draft	Report on voting
65E/440/DTR	65E/514/RVC

Full information on the voting for the approval of this technical report can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

The list of all parts of the IEC 62453 series, under the general title *Field device tool (FDT) interface specification*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

INTRODUCTION

This part of IEC 62453 is an interface specification for developers of Field Device Tool (FDT) components for function control and data access within a client/server architecture. The specification is a result of an analysis and design process to develop standard interfaces to facilitate the development of servers and clients by multiple vendors that need to interoperate seamlessly.

With the integration of fieldbuses into control systems, there are a few other tasks which need to be performed. In addition to fieldbus- and device-specific tools, there is a need to integrate these tools into higher-level system-wide planning or engineering tools. In particular, for use in extensive and heterogeneous control systems, typically in the area of the process industry, the unambiguous definition of engineering interfaces that are easy to use for all those involved is of great importance.

A device-specific software component, called Device Type Manager (DTM), is supplied by the field device manufacturer with its device. The DTM is integrated into engineering tools via the FDT interfaces defined in this specification. The approach to integration is in general open for all kind of fieldbuses and thus meets the requirements for integrating different kinds of devices into heterogeneous control systems.

Figure 1 shows how this part of IEC 62453-51-xy series is aligned in the structure of the IEC 62453 series.

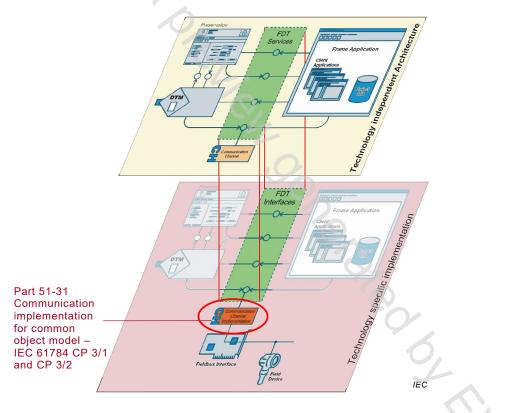


Figure 1 – Part 51-31 of the IEC 62453 series